



PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Tongbi JIANG

Serial No.: 09/484,437

Filed: January 18, 2000

Title: DIE ATTACH CURE METHOD FOR
SEMICONDUCTOR DEVICE

Art Unit: 2822

Examiner: J. Mitchell

REQUEST FOR DRAWINGS CHANGE

Commissioner for Patents
Washington, D.C. 20231

Sir:

Applicant proposes to substitute the enclosed drawing (FIG. 1) for the originally-filed Figure 1. The Examiner's approval is solicited.

The enclosed drawing includes a change which is consistent with the original drawings. Furthermore, the enclosed drawing contains no new matter. The proposed drawings change is provided to insure complete compliance to 37 C.F.R. §§ 1.83 and 1.84.

Allowance of the drawings change is solicited.

Respectfully submitted,

By: 

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